

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. . . . . 09/784,234  
Filing Date . . . . . February 14, 2001  
Inventor . . . . . Shozo Nagano et al.  
Assignee . . . . . Honeywell International, Inc.  
Group Art Unit . . . . . ~~Unknown~~  
Examiner . . . . . ~~Unknown~~  
Attorney's Docket No. . . . . 30-5000-(4015)-Div1  
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating  
Anodes, Metal Alloys For Use as a Conductive Interconnection in an  
Integrated Circuit, and Physical Vapor Deposition Targets

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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

References -- See Attached Form PTO-1449

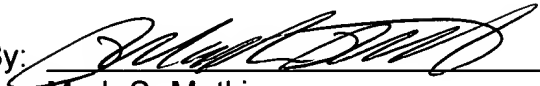
The attached form PTO-1449 is submitted in compliance with 37 CFR § 1.56. Copies of the cited prior art references are attached. No admission is made regarding whether the submitted references are prior art.

This Supplemental Information Disclosure Statement is being filed within three months of the filing date of the application or before the mailing of a first Office Action, whichever occurs last. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this Supplemental Information Disclosure Statement, please charge the fee specified under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925. Please credit Deposit Account No. 23-0925 with any overpayment of the above fee.

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 5-101

By:   
Mark S. Matkin  
Reg. No. 32,268